

# PS7200B-1A

# 4-PIN SOP 1.0 Ω LOW ON-STATE RESISTANCE 1-ch Optical Coupled MOS FET

## DESCRIPTION

NEC

The PS7200B-1A is a low on-state resistance solid state relay containing GaAs LEDs on the light emitting side (input side) and MOS FETs on the output side.

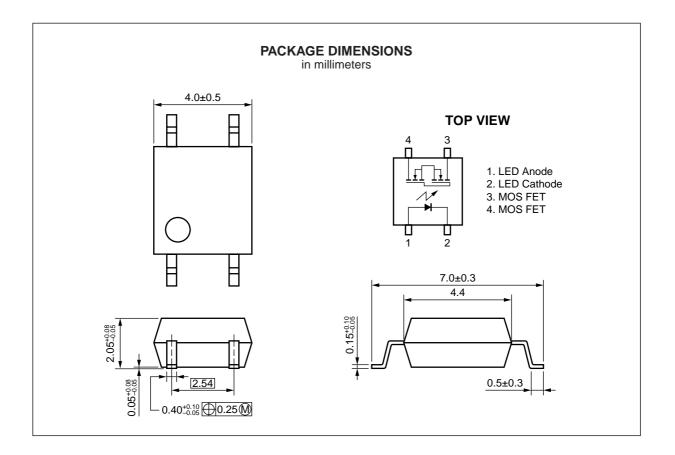
It is suitable for high-frequency signal control due to its low  $C \times R$ , low on-state resistance, and low off-state leakage current.

## ★ FEATURES

- Low  $C \times R$  ( $C \times R = 32 \text{ pF} \cdot \Omega$ )
- Low on-state resistance ( $R_{on} = 1.0 \Omega TYP.$ )
- Low off-state leakage current (ILoff = 0.1 nA TYP.)
- High-speed turn-on time (ton = 0.05 ms TYP.)
- 1 channel type (1 a output)
- Low LED operating current (IF = 2 mA)
- Designed for AC/DC switching line changer
- Small and thin package (4-pin SOP, Height = 2.1 mm)
- · Low offset voltage
- Ordering number of taping product: PS7200B-1A-E3, E4, F3, F4
- UL approved: File No. E72422 (S)
- BSI approved: No. 8241/8242
- CSA approved: No. CA 101391

## **APPLICATIONS**

• Measurement equipment



## **★** ORDERING INFORMATION

Part Number	Package	Packing Style	Application Part Number <sup>*1</sup>
PS7200B-1A	4-pin SOP	Magazine case 100 pcs	PS7200B-1A
PS7200B-1A-E3		Embossed Tape 900 pcs/reel	
PS7200B-1A-E4			
PS7200B-1A-F3		Embossed Tape 3 500 pcs/reel	
PS7200B-1A-F4			

\*1 For the application of the Safety Standard, following part number should be used.

## ABSOLUTE MAXIMUM RATINGS (TA = 25 °C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit	
Diode	Forward Current (DC)	lF	50	mA	
	Reverse Voltage	VR	5.0	V	
	Power Dissipation	PD	50	mW	
	Peak Forward Current <sup>*1</sup>	<b>I</b> FP	1	А	
MOS FET	IOS FET Break Down Voltage		40	V	
	Continuous Load Current	١L	250	mA	
	Pulse Load Current <sup>*2</sup> (AC/DC Connection)	Ilp	500	mA	
	Power Dissipation	PD	100	mW	
Isolation Voltage <sup>*3</sup>		BV	1 500	Vr.m.s.	
Total Power Dissipation		Рт	150	mW	
Operating Ambient Temperature		TA	-40 to +80	°C	
Storage Temperature		Tstg	-40 to +100	°C	

\*1 PW = 100  $\mu$ s, Duty Cycle = 1 %

\*2 PW = 100 ms, 1 shot

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\*3 AC voltage for 1 minute at TA = 25 °C, RH = 60 % between input and output

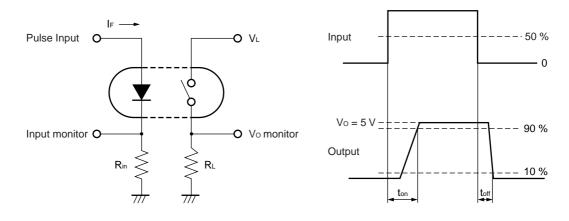
## **RECOMMENDED OPERATING CONDITIONS (TA = 25 °C)**

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	lF	2	10	20	mA
LED Off Voltage	VF	0		0.5	V

# ★ ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C)

	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	IF = 10 mA		1.2	1.4	V
	Reverse Current	Ir	V <sub>R</sub> = 5 V			5.0	μA
MOS FET	Off-state Leakage Current	Loff	V <sub>D</sub> = 40 V		0.1	100	nA
	Output Capacitance	Cout	V <sub>D</sub> = 0 V, f = 1 MHz		32		pF
Coupled	LED On-state Current	IFon	I∟ = 250 mA			2.0	mA
	On-state Resistance	Ron1	IF = 10 mA, IL = 10 mA		1.0	1.5	Ω
		Ron2	$I_{\text{F}}$ = 10 mA, $I_{\text{L}}$ = 250 mA, $t \leq$ 10 ms				
	Turn-on Time <sup>*1</sup>	ton	$I_F$ = 10 mA, Vo = 5 V, PW $\geq$ 10 ms		0.05	1.0	ms
	Turn-off Time <sup>*1</sup>	toff			0.02	0.2	
	Isolation Resistance	Ri-o	VI-O = 1.0 kVDC	10 <sup>°</sup>			Ω
	Isolation Capacitance	CI-0	V = 0 V, f = 1 MHz		0.5		pF

\*1 Test Circuit for Switching Time

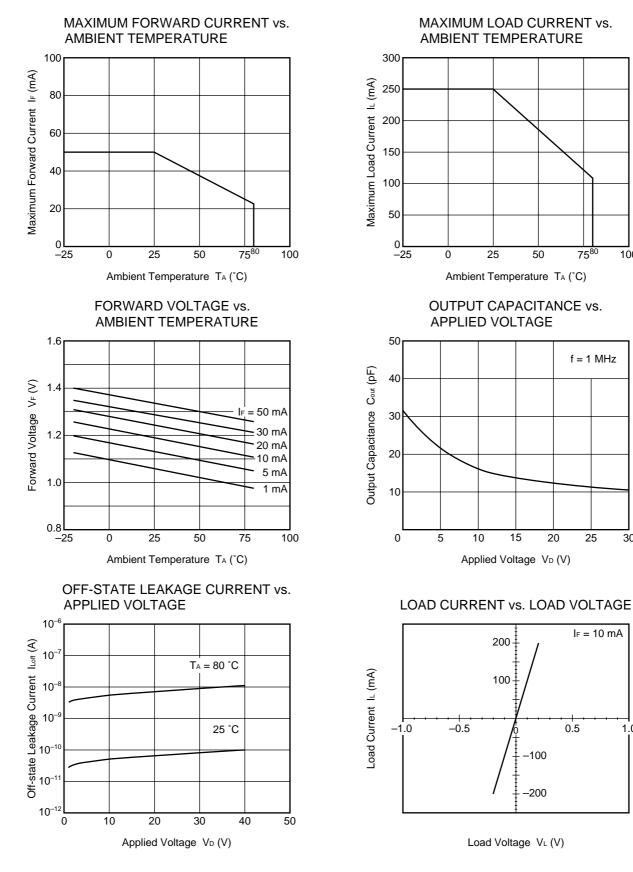


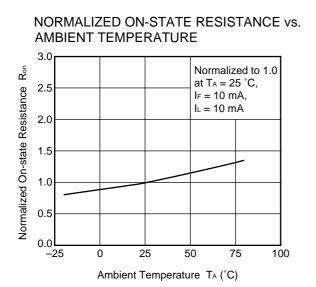
100

30

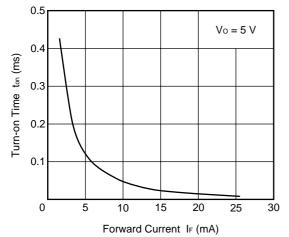
1.0

## TYPICAL CHARACTERISTICS (TA = 25 °C, unless otherwise specified)

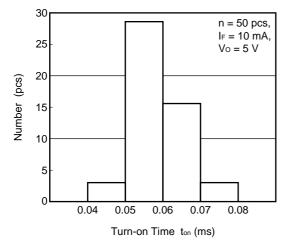




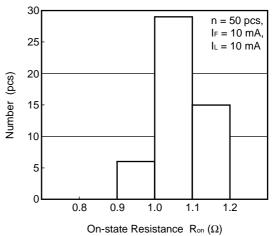
TURN-ON TIME vs. FORWARD CURRENT



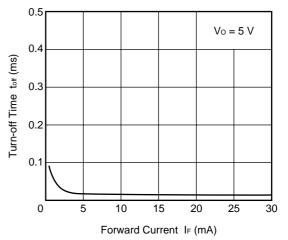
#### TURN-ON TIME DISTRIBUTION



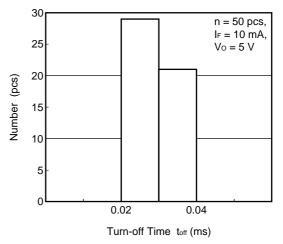
**ON-STATE RESISTANCE DISTRIBUTION** 

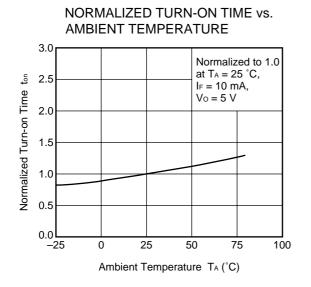


TURN-OFF TIME vs. FORWARD CURRENT

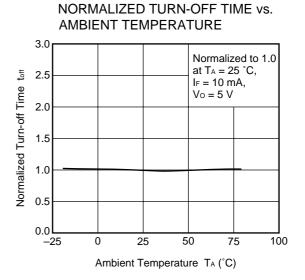


TURN-OFF TIME DISTRIBUTION

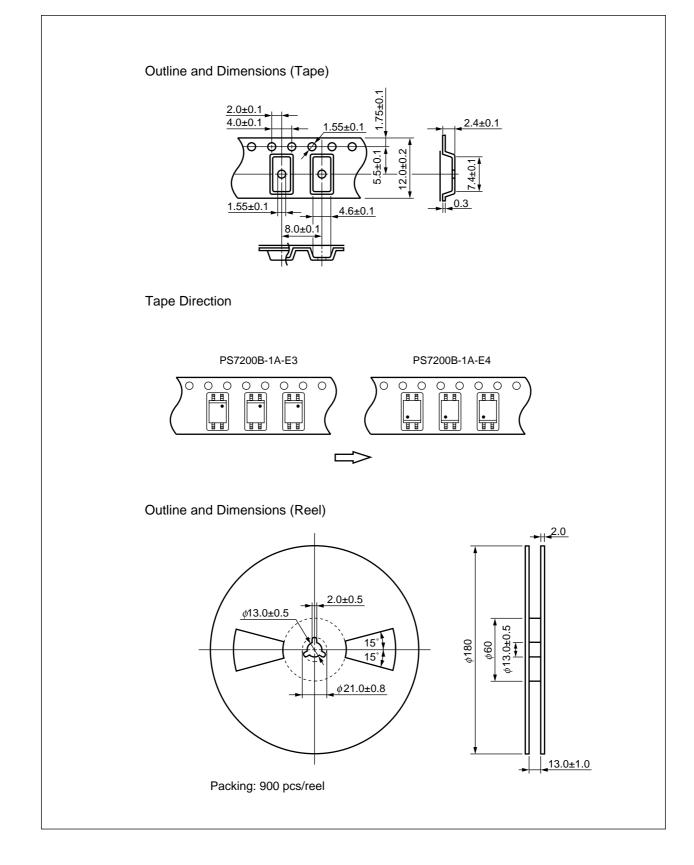


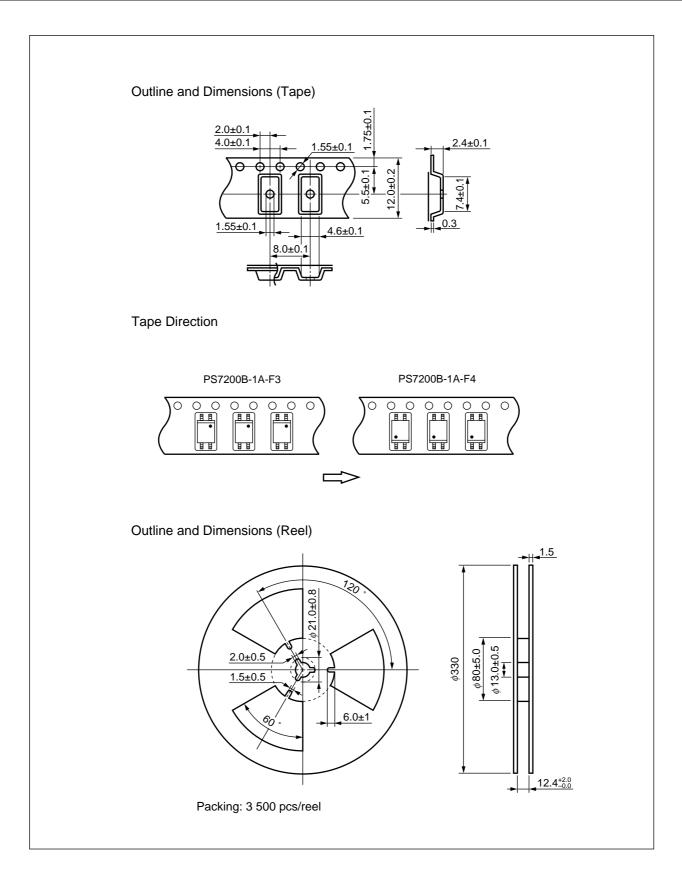


**Remark** The graphs indicate nominal characteristics.



## ★ TAPING SPECIFICATIONS (in millimeters)





## ★ RECOMMENDED SOLDERING CONDITIONS

## (1) Infrared reflow soldering

Peak reflow temperature
 235 °C (package surface temperature)

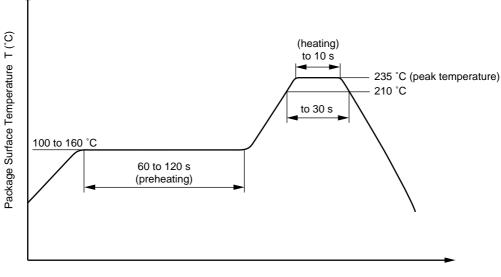
Two

- Time of temperature higher than 210 °C
- Number of reflows
- Flux

Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt % is recommended.)

## Recommended Temperature Profile of Infrared Reflow

30 seconds or less





#### (2) Dip soldering

## • Temperature 260 °C or below (molten solder temperature)

- Time
- 10 seconds or less
- Number of times One
- Flux

Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt % is recommended.)

## (3) Cautions

• Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

[MEMO]

## CAUTION

Within this device there exists GaAs (Gallium Arsenide) material which is a harmful substance if ingested. Please do not under any circumstances break the hermetic seal.

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